

Abstract

SEMICONDUCTOR DEVICE AND METHOD OF FORMING ADHESIVE MATERIAL OVER SEMICONDUCTOR DIE AND CARRIER TO REDUCE DIE SHIFTING DURING ENCAPSULATION

A semiconductor device has a plurality of semiconductor die mounted to a carrier. An adhesive material is deposited over a portion of the semiconductor die and carrier to secure the semiconductor die to the carrier. The adhesive material is deposited over a side of the semiconductor die and over a surface of the carrier. The adhesive material can be deposited over a corner of the semiconductor die, or over a side of the semiconductor die, or around a perimeter of the semiconductor die. An encapsulant is deposited over the semiconductor die and carrier. The adhesive material reduces shifting of the semiconductor die with respect to the carrier during encapsulation. The adhesive material is cured and the carrier is removed. The adhesive material can also be removed. An interconnect structure is formed over the semiconductor die and encapsulant. The semiconductor die are singulated through the encapsulant and interconnect structure.

(Fig 7)